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In the Claims

The claims currently pending in the application are as follows:

1. (currently amended) A method for fabricating a device, the method comprising:
providing a substantially planar substrate having opposed major surfaces, the substrate
comprising a through hole extending between the major surfaces;

filling the through hole with a conductive interconnecting element; and

5 after the filling, forming a conductive die mounting pad and a conductive connecting
pad on different ones of the major surfaces in electrical contact with the conductive
interconnecting element.

2. (original) The method of claim 1, in which the providing comprises forming the
through hole in the substrate by one of punching and drilling.

3. (original) The method of claim 1, in which the filling comprises filling the through
hole with the conductive interconnecting element by at least one of pressing, metal deposition,
screen printing and plating.

4. (previously presented) The method of claim 1, in which the forming comprises
forming the conductive die mounting pad and the conductive connecting pad by at least one of
plating, cladding and screen printing.

5. (original) The method of claim 1, in which the providing comprises:
providing the substrate of unfired ceramic; and
forming the through hole in the unfired ceramic.

6. (original) The method of claim 5, in which the filling comprising filling the
through hole in the unfired ceramic.

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7. (previously presented) The method of claim 6, in which:
the forming comprises forming a seed layer on the unfired ceramic;
the method additionally comprises firing the ceramic; and
the forming additionally comprises forming additional layers on the seed layer after the
5 firing.

8. (original) The method of claim 7, in which:
the seed layer is formed by screen printing; and
the additional layers are formed by plating.

9. (withdrawn-previously presented) The method of claim 1, additionally comprising
attaching a semiconductor die to the die mounting pad.

10. (withdrawn) The method of claim 9, additionally comprising:
providing a packaging device, the packaging device including a conductive mounting
surface; and
mounting the device in the packaging device, the mounting comprising attaching the
5 connecting pad to the conductive mounting surface of the packaging device.

11. (withdrawn) The method of claim 9, in which:
providing a substrate comprises providing a wafer of which the substrate constitutes
part; and
the method additionally comprises, after the filling, the forming and the attaching,
5 singulating the wafer into individual devices.

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12. (currently amended) The method of claim 1, in which:
in providing a substrate, the substrate additionally comprises an additional through hole;
the method additionally comprises filling the additional through hole with an
5 additional conductive interconnecting element; and
the forming additionally comprises, after the filling, forming a conductive bonding pad
and an additional conductive connecting pad on the different ones of the opposed surfaces of
the substrate in electrical contact with the additional conductive interconnecting element.
13. (withdrawn-previously presented) The method of claim 12, additionally
comprising attaching a semiconductor die to the die mounting pad.
14. (withdrawn) The method of claim 13, additionally comprising connecting a
bonding wire between the semiconductor die and the bonding pad.
15. (withdrawn) The method of claim 14, in which:
providing a substrate comprises providing a wafer of which the substrate constitutes
part; and
the method additionally comprises, after the filling, the forming and the attaching and
5 the connecting, singulating the wafer into individual devices.
16. (withdrawn) The method of claim 15, additionally comprising performing
electrical testing prior to the singulating.
17. (withdrawn) The method of claim 15, additionally comprising performing electro-
optical testing prior to the singulating.
18. (withdrawn-previously presented) The method of claim 14, additionally
comprising encapsulating the semiconductor die and at least a portion of the major surface of
the substrate on which the die mounting pad is located.

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19. (original) The method of claim 1, in which:
providing a substrate comprises providing a wafer of which the substrate constitutes part;
and
the method additionally comprises, after the filling and the forming, singulating the wafer
into individual devices.

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